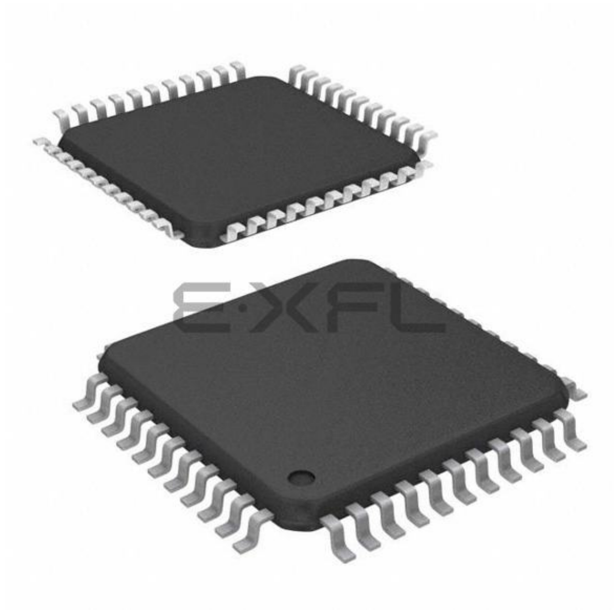

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	C251
Core Size	8/16-Bit
Speed	16MHz
Connectivity	EBI/EMI, I²C, Microwire, SPI, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	32
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	44-VQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/tsc80251g2d-l16ce

Block Diagram

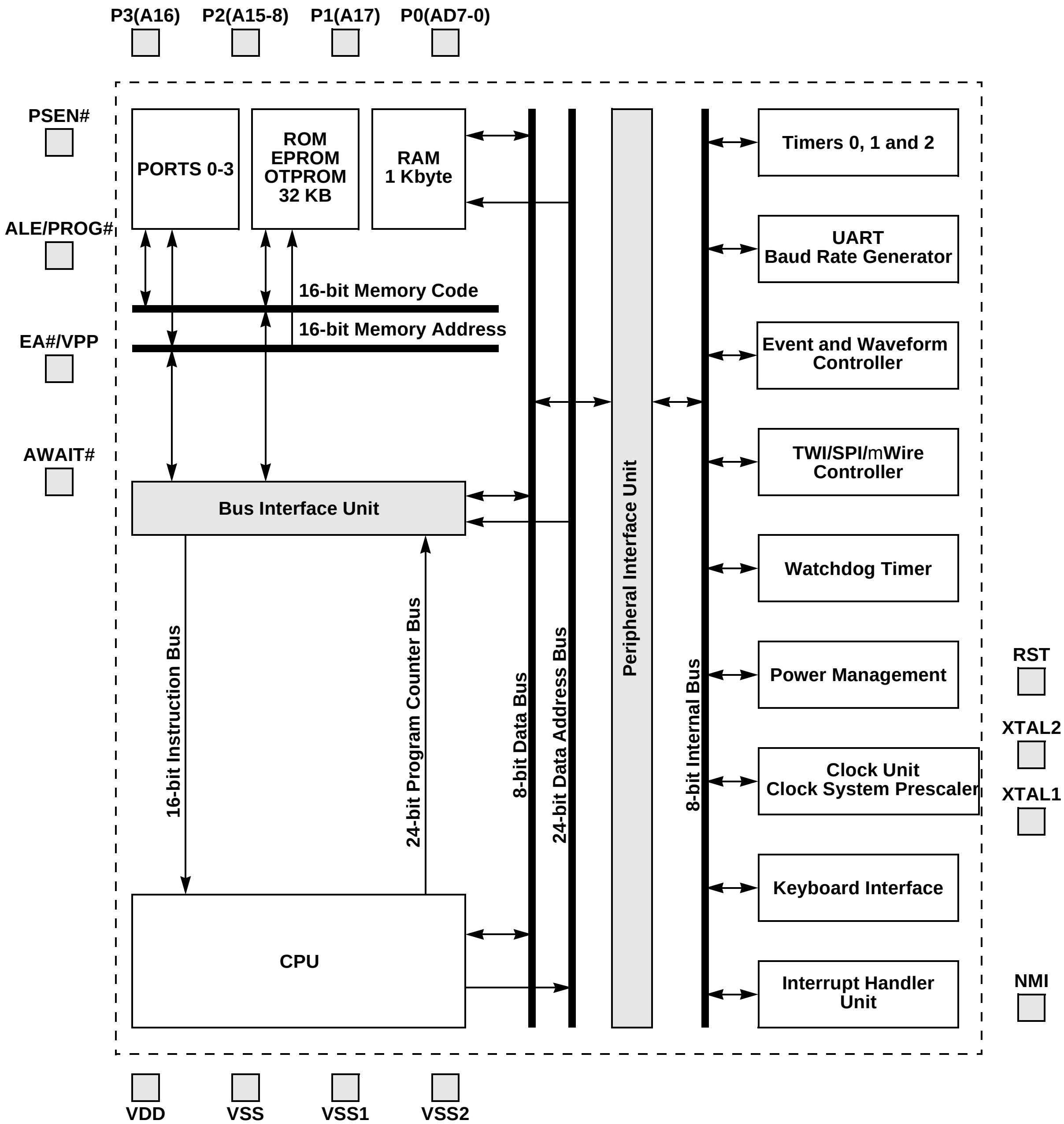


Table 1. TSC80251G2D Pin Assignment

DIP	PLCC	VQFP	Name	DIP	PLCC	VQFP	Name
	1	39	VSS1		23	17	VSS2
1	2	40	P1.0/T2	21	24	18	P2.0/A8
2	3	41	P1.1/T2EX	22	25	19	P2.1/A9
3	4	42	P1.2/ECI	23	26	20	P2.2/A10
4	5	43	P1.3/CEX0	24	27	21	P2.3/A11
5	6	44	P1.4/CEX1/SS#	25	28	22	P2.4/A12
6	7	1	P1.5/CEX2/MISO	26	29	23	P2.5/A13
7	8	2	P1.6/CEX3/SCL/SCK/WAIT#	27	30	24	P2.6/A14
8	9	3	P1.7/A17/CEX4/SDA/MOSI/WCLK	28	31	25	P2.7/A15
9	10	4	RST	29	32	26	PSEN#
10	11	5	P3.0/RXD	30	33	27	ALE/PROG#
	12	6	AWAIT#		34	28	NMI
11	13	7	P3.1/TXD	31	35	29	EA#/VPP
12	14	8	P3.2/INT0#	32	36	30	P0.7/AD7
13	15	9	P3.3/INT1#	33	37	31	P0.6/AD6
14	16	10	P3.4/T0	34	38	32	P0.5/AD5
15	17	11	P3.5/T1	35	39	33	P0.4/AD4
16	18	12	P3.6/WR#	36	40	34	P0.3/AD3
17	19	13	P3.7/A16/RD#	37	41	35	P0.2/AD2
18	20	14	XTAL2	38	42	36	P0.1/AD1
19	21	15	XTAL1	39	43	37	P0.0/AD0
20	22	16	VSS	40	44	38	VDD

Table 2. Product Name Signal Description (Continued)

Signal Name	Type	Description	Alternate Function
T1:0	I/O	**Timer 1:0 External Clock Inputs** When timer 1:0 operates as a counter, a falling edge on the T1:0 pin increments the count.	–
T2	I/O	**Timer 2 Clock Input/Output** For the timer 2 capture mode, T2 is the external clock input. For the Timer 2 clock-out mode, T2 is the clock output.	P1.0
T2EX	I	**Timer 2 External Input** In timer 2 capture mode, a falling edge initiates a capture of the timer 2 registers. In auto-reload mode, a falling edge causes the timer 2 register to be reloaded. In the up-down counter mode, this signal determines the count direction: 1 = up, 0 = down.	P1.1
TXD	O	**Transmit Serial Data** TXD outputs the shift clock in serial I/O mode 0 and transmits data in serial I/O modes 1, 2 and 3.	P3.1
VDD	PWR	**Digital Supply Voltage** Connect this pin to +5V or +3V supply voltage.	–
VPP	I	**Programming Supply Voltage** The programming supply voltage is applied to this input for programming the on-chip EPROM/OTPROM.	–
VSS	GND	**Circuit Ground** Connect this pin to ground.	–
VSS1	GND	**Secondary Ground 1** This ground is provided to reduce ground bounce and improve power supply bypassing. Connection of this pin to ground is recommended. However, when using the TSC80251G2D as a pin-for-pin replacement for a 8xC51 product, VSS1 can be unconnected without loss of compatibility. Not available on DIP package.	–
VSS2	GND	**Secondary Ground 2** This ground is provided to reduce ground bounce and improve power supply bypassing. Connection of this pin to ground is recommended. However, when using the TSC80251G2D as a pin-for-pin replacement for a 8xC51 product, VSS2 can be unconnected without loss of compatibility. Not available on DIP package.	–
WAIT#	I	**Real-time Synchronous Wait States Input** The real-time WAIT# input is enabled by setting RTWE bit in WCON (S:A7h). During bus cycles, the external memory system can signal ‘system ready’ to the microcontroller in real time by controlling the WAIT# input signal.	P1.6
WCLK	O	**Wait Clock Output** The real-time WCLK output is enabled by setting RTWCE bit in WCON (S:A7h). When enabled, the WCLK output produces a square wave signal with a period of one half the oscillator frequency.	P1.7
WR#	O	**Write** Write signal output to external memory.	P3.6
XTAL1	I	**Input to the on-chip inverting oscillator amplifier** To use the internal oscillator, a crystal/resonator circuit is connected to this pin. If an external oscillator is used, its output is connected to this pin. XTAL1 is the clock source for internal timing.	–

Address Spaces

The TSC80251G2D derivatives implement four different address spaces:

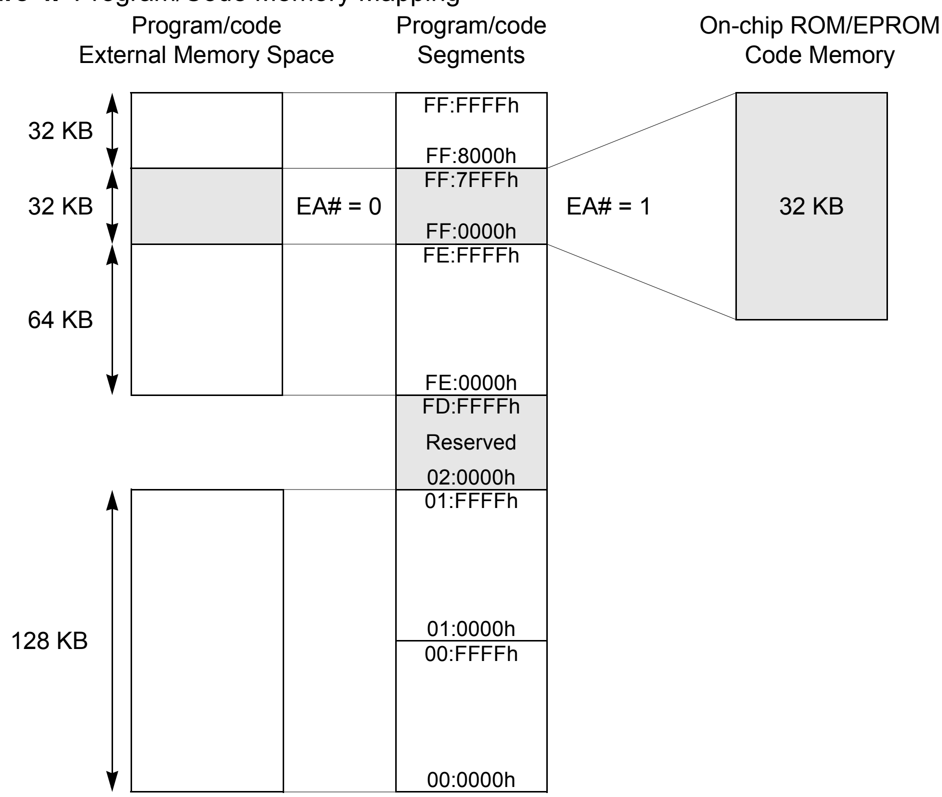
- On-chip ROM program/code memory (not present in ROMless devices)
- On-chip RAM data memory
- Special Function Registers (SFRs)
- Configuration array

Program/Code Memory

The TSC83251G2D and TSC87251G2D implement 32 KB of on-chip program/code memory. Figure 4 shows the split of the internal and external program/code memory spaces. If EA# is tied to a high level, the 32-Kbyte on-chip program memory is mapped in the lower part of segment FF: where the C251 core jumps after reset. The rest of the program/code memory space is mapped to the external memory. If EA# is tied to a low level, the internal program/code memory is not used and all the accesses are directed to the external memory.

The TSC83251G2D products provide the internal program/code memory in a masked ROM memory while the TSC87251G2D products provide it in an EPROM memory. For the TSC80251G2D products, there is no internal program/code memory and EA# must be tied to a low level.

Figure 4. Program/Code Memory Mapping



Note: Special care should be taken when the Program Counter (PC) increments:
If the program executes exclusively from on-chip code memory (not from external memory), beware of executing code from the upper eight bytes of the on-chip ROM (FF:7FF8h-FF:7FFFh). Because of its pipeline capability, the TSC80251G2D derivative may attempt to prefetch code from external memory (at an address above FF:7FFFh) and thereby disrupt I/O Ports 0 and 2. Fetching code constants from these 8 bytes does not affect Ports 0 and 2.
When PC reaches the end of segment FF:, it loops to the reset address FF:0000h (for

Special Function Registers

The Special Function Registers (SFRs) of the TSC80251G2D derivatives fall into the categories detailed in Table 1 to Table 9.

SFRs are placed in a reserved on-chip memory region S: which is not represented in the data memory mapping (Figure 5). The relative addresses within S: of these SFRs are provided together with their reset values in Table . They are upward compatible with the SFRs of the standard 80C51 and the Intel's 80C251Sx family. In this table, the C251 core registers are identified by Note 1 and are described in the TSC80251 Programmer's Guide. The other SFRs are described in the TSC80251G1D Design Guide. All the SFRs are bit-addressable using the C251 instruction set.

Table 1. C251 Core SFRs

Mnemonic	Name	Mnemonic	Name
ACC(1)	Accumulator	SPH(1)	Stack Pointer High - MSB of SPX
B(1)	B Register	DPL(1)	Data Pointer Low byte - LSB of DPTR
PSW	Program Status Word	DPH(1)	Data Pointer High byte - MSB of DPTR
PSW1	Program Status Word 1	DPXL(1)	Data Pointer Extended Low byte of DPX - Region number
SP(1)	Stack Pointer - LSB of SPX		

Note: 1. These SFRs can also be accessed by their corresponding registers in the register file.

Table 2. I/O Port SFRs

Mnemonic	Name	Mnemonic	Name
P0	Port 0	P2	Port 2
P1	Port 1	P3	Port 3

Table 3. Timers SFRs

Mnemonic	Name	Mnemonic	Name
TL0	Timer/Counter 0 Low Byte	TMOD	Timer/Counter 0 and 1 Modes
TH0	Timer/Counter 0 High Byte	T2CON	Timer/Counter 2 Control
TL1	Timer/Counter 1 Low Byte	T2MOD	Timer/Counter 2 Mode
TH1	Timer/Counter 1 High Byte	RCAP2L	Timer/Counter 2 Reload/Capture Low Byte
TL2	Timer/Counter 2 Low Byte	RCAP2H	Timer/Counter 2 Reload/Capture High Byte
TH2	Timer/Counter 2 High Byte	WDTRST	WatchDog Timer Reset
TCON	Timer/Counter 0 and 1 Control		

Table 4. Serial I/O Port SFRs

Mnemonic	Name
SCON	Serial Control
SBUF	Serial Data Buffer
SADEN	Slave Address Mask

Mnemonic	Name
SADDR	Slave Address
BRL	Baud Rate Reload
BDRCON	Baud Rate Control

Table 5. SSLC SFRs

Mnemonic	Name
SSCON	Synchronous Serial control
SSDAT	Synchronous Serial Data
SSCS	Synchronous Serial Control and Status

Mnemonic	Name
SSADR	Synchronous Serial Address
SSBR	Synchronous Serial Bit Rate

Table 6. Event Waveform Control SFRs

Mnemonic	Name
CCON	EWC-PCA Timer/Counter Control
CMOD	EWC-PCA Timer/Counter Mode
CL	EWC-PCA Timer/Counter Low Register
CH	EWC-PCA Timer/Counter High Register
CCAPM0	EWC-PCA Timer/Counter Mode 0
CCAPM1	EWC-PCA Timer/Counter Mode 1
CCAPM2	EWC-PCA Timer/Counter Mode 2
CCAPM3	EWC-PCA Timer/Counter Mode 3
CCAPM4	EWC-PCA Timer/Counter Mode 4

Mnemonic	Name
CCAP0L	EWC-PCA Compare Capture Module 0 Low Register
CCAP1L	EWC-PCA Compare Capture Module 1 Low Register
CCAP2L	EWC-PCA Compare Capture Module 2 Low Register
CCAP3L	EWC-PCA Compare Capture Module 3 Low Register
CCAP4L	EWC-PCA Compare Capture Module 4 Low Register
CCAP0H	EWC-PCA Compare Capture Module 0 High Register
CCAP1H	EWC-PCA Compare Capture Module 1 High Register
CCAP2H	EWC-PCA Compare Capture Module 2 High Register
CCAP3H	EWC-PCA Compare Capture Module 3 High Register
CCAP4H	EWC-PCA Compare Capture Module 4 High Register

Table 10. SFR Descriptions

	0/8	1/9	2/A	3/B	4/C	5/D	6/E	7/F	
F8h		CH 0000 0000	CCAP0H 0000 0000	CCAP1H 0000 0000	CCAP2H 0000 0000	CCAP3H 0000 0000	CCAP4H 0000 0000		FFh
F0h	B(1) 0000 0000								F7h
E8h		CL 0000 0000	CCAP0L 0000 0000	CCAP1L 0000 0000	CCAP2L 0000 0000	CCAP3L 0000 0000	CCAP4L 0000 0000		EFh
E0h	ACC(1) 0000 0000								E7h
D8h	CCON 00X0 0000	CMOD 00XX X000	CCAPM0 X000 0000	CCAPM1 X000 0000	CCAPM2 X000 0000	CCAPM3 X000 0000	CCAPM4 X000 0000		DFh
D0h	PSW(1) 0000 0000	PSW1(1) 0000 0000							D7h
C8h	T2CON 0000 0000	T2MOD XXXX XX00	RCAP2L 0000 0000	RCAP2H 0000 0000	TL2 0000 0000	TH2 0000 0000			CFh
C0h									C7h
B8h	IPL0 X000 0000	SADEN 0000 0000					SPH(1) 0000 0000		BFh
B0h	P3 1111 1111	IE1 XX0X XXX0	IPL1 XX0X XXX0	IPH1 XX0X XXX0				IPH0 X000 0000	B7h
A8h	IE0 0000 0000	SADDR 0000 0000							AFh
A0h	P2 1111 1111						WDTRST 1111 1111	WCON XXXX XX00	A7h
98h	SCON 0000 0000	SBUF XXXX XXXX	BRL 0000 0000	BDRCON XXX0 0000	P1LS 0000 0000	P1IE 0000 0000	P1F 0000 0000		9Fh
90h	P1 1111 1111		SSBR 0000 0000	SSCON(2)	SSCS(3)	SSDAT 0000 0000	SSADR 0000 0000		97h
88h	TCON 0000 0000	TMOD 0000 0000	TL0 0000 0000	TL1 0000 0000	TH0 0000 0000	TH1 0000 0000	CKRL 0000 1000	POWM 0XXX XXXX	8Fh
80h	P0 1111 1111	SP(1) 0000 0111	DPL(1) 0000 0000	DPH(1) 0000 0000	DPXL(1) 0000 0001			PCON 0000 0000	87h
	0/8	1/9	2/A	3/B	4/C	5/D	6/E	7/F	

Reserved

Notes:
1. These registers are described in the TSC80251 Programmer's Guide (C251 core registers).
2. In TWI and SPI modes, SSCON is splitted in two separate registers. SSCON reset value is 0000 0000 in TWI mode and 0000 0100 in SPI mode.
3. In read and write modes, SSCS is splitted in two separate registers. SSCS reset value is 1111 1000 in read mode and 0000 0000 in write mode.

Configuration Bytes

The TSC80251G2D derivatives provide user design flexibility by configuring certain operating features at device reset. These features fall into the following categories:

- external memory interface (Page mode, address bits, programmed wait states and the address range for RD#, WR#, and PSEN#)
- source mode/binary mode opcodes
- selection of bytes stored on the stack by an interrupt
- mapping of the upper portion of on-chip code memory to region 00:

Two user configuration bytes UCONFIG0 (see Table 11) and UCONFIG1 (see Table 12) provide the information.

When EA# is tied to a low level, the configuration bytes are fetched from the external address space. The TSC80251G2D derivatives reserve the top eight bytes of the memory address space (FF:FFF8h-FF:FFFFh) for an external 8-byte configuration array. Only two bytes are actually used: UCONFIG0 at FF:FFF8h and UCONFIG1 at FF:FFF9h.

For the mask ROM devices, configuration information is stored in on-chip memory (see ROM Verifying). When EA# is tied to a high level, the configuration information is retrieved from the on-chip memory instead of the external address space and there is no restriction in the usage of the external memory.

Table 24. Summary of Multiply, Divide and Decimal-adjust Instructions

MultiplyMUL AB(B:A) $\leftarrow$ (A)$\times$(B)
MUL <dest>, <src>extended dest opnd $\leftarrow$ dest opnd $\times$ src opnd

DivideDIV AB(A) $\leftarrow$ Quotient ((A)/(B))
(B) $\leftarrow$ Remainder ((A)/(B))

DivideDIV <dest>, <src>ext. dest opnd high $\leftarrow$ Quotient (dest opnd/src opnd)
ext. dest opnd low $\leftarrow$ Remainder (dest opnd/src opnd)

Decimal-adjust ACCDA AIF [[$(A)_{3:0}$ > 9] $\vee$ [(AC) = 1]]
for Addition (BCD) THEN $(A)_{3:0} \leftarrow (A)_{3:0}$ + 6 !affects CY;
IF [[$(A)_{7:4}$ > 9] $\vee$ [(CY) = 1]]
THEN $(A)_{7:4} \leftarrow (A)_{7:4}$ + 6

Mnemonic	<dest>, <src>[1]	Comments	Binary Mode		Source Mode	
			Bytes	States	Bytes	States
MUL	AB	Multiply A and B	1	5	1	5
	Rmd, Rms	Multiply byte register and byte register	3	6	2	5
	WRjd, WRjs	Multiply word register and word register	3	12	2	11
DIV	AB	Divide A and B	1	10	1	10
	Rmd, Rms	Divide byte register and byte register	3	11	2	10
	WRjd, WRjs	Divide word register and word register	3	21	2	20
DA	A	Decimal adjust ACC	1	1	1	1

Note: 1. A shaded cell denotes an instruction in the C51 Architecture.

Table 26. Summary of Move Instructions (2/3)

Move[1]MOV <dest>, <src>dest opnd ← src opnd						
			Binary Mode		Source Mode	
Mnemonic	**<dest>, <src>[2]**	**Comments**	**Bytes**	**States**	**Bytes**	**States**
MOV	A, Rn	Register to ACC	1	1	2	2
	A, dir8	Direct address (on-chip RAM or SFR) to ACC	2	1[3]	2	1[3]
	A, at Ri	Indirect address to ACC	1	2	2	3
	A, #data	Immediate data to ACC	2	1	2	1
	Rn, A	ACC to register	1	1	2	2
	Rn, dir8	Direct address (on-chip RAM or SFR) to register	2	1[3]	3	2[3]
	Rn, #data	Immediate data to register	2	1	3	2
	dir8, A	ACC to direct address (on-chip RAM or SFR)	2	2[3]	2	2[3]
	dir8, Rn	Register to direct address (on-chip RAM or SFR)	2	2[3]	3	3[3]
	dir8, dir8	Direct address to direct address (on-chip RAM or SFR)	3	3[4]	3	3[4]
	dir8, at Ri	Indirect address to direct address (on-chip RAM or SFR)	2	3[3]	3	4[3]
	dir8, #data	Immediate data to direct address (on-chip RAM or SFR)	3	3[3]	3	3[3]
	at Ri, A	ACC to indirect address	1	3	2	4
	at Ri, dir8	Direct address (on-chip RAM or SFR) to indirect address	2	3[3]	3	4[3]
	at Ri, #data	Immediate data to indirect address	2	3	3	4
	DPTR, #data16	Load Data Pointer with a 16-bit constant	3	2	3	2

Notes:
1. Instructions that move bits are in Table 27.
2. Move instructions from the C51 Architecture.
3. If this instruction addresses an I/O Port (Px, x = 0-3), add 1 to the number of states. Add 2 if it addresses a Peripheral SFR.
4. Apply note 3 for each dir8 operand.

Table 29. Summary of Conditional Jump Instructions (1/2)

Jump conditional on statusJcc rel(PC) ← (PC) + size (instr); IF [cc] THEN (PC) ← (PC) + rel						
			Binary Mode		Source Mode	
Mnemonic	<dest>, <src>(1)	Comments	Bytes	States	Bytes	States
JC	rel	Jump if carry	2	1/4(3)	2	1/4(3)
JNC	rel	Jump if not carry	2	1/4(3)	2	1/4(3)
JE	rel	Jump if equal	3	2/5(3)	2	1/4(3)
JNE	rel	Jump if not equal	3	2/5(3)	2	1/4(3)
JG	rel	Jump if greater than	3	2/5(3)	2	1/4(3)
JLE	rel	Jump if less than, or equal	3	2/5(3)	2	1/4(3)
JSL	rel	Jump if less than (signed)	3	2/5(3)	2	1/4(3)
JSLE	rel	Jump if less than, or equal (signed)	3	2/5(3)	2	1/4(3)
JSG	rel	Jump if greater than (signed)	3	2/5(3)	2	1/4(3)
JSGE	rel	Jump if greater than or equal (signed)	3	2/5(3)	2	1/4(3)

Notes:
1. A shaded cell denotes an instruction in the C51 Architecture.
2. States are given as jump not-taken/taken.
3. In internal execution only, add 1 to the number of states of the 'jump taken' if the destination address is internal and odd.

AC Characteristics - Commercial & Industrial

AC Characteristics - External Bus Cycles

Definition of Symbols

Table 38. External Bus Cycles Timing Symbol Definitions

Signals	
A	Address
D	Data In
L	ALE
Q	Data Out
R	RD#/PSEN#
W	WR#

Conditions	
H	High
L	Low
V	Valid
X	No Longer Valid
Z	Floating

Timings

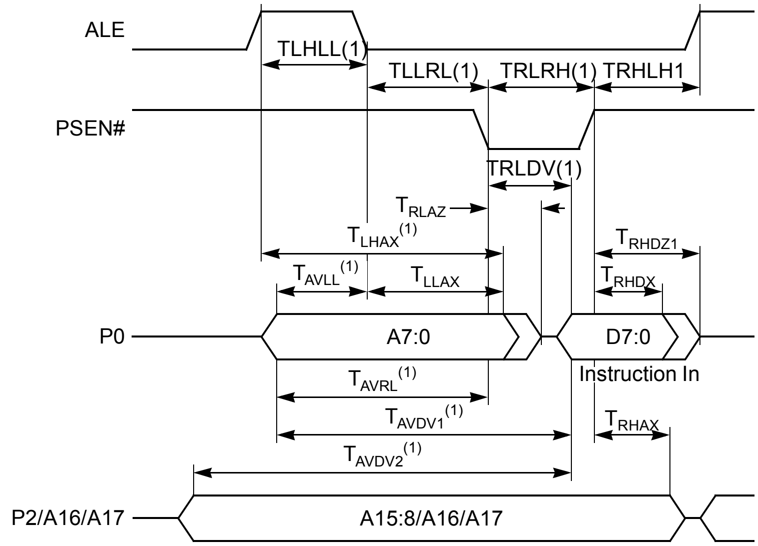
Test conditions: capacitive load on all pins = 50 pF.

Table 39 and Table 40 list the AC timing parameters for the TSC80251G2D derivatives with no wait states. External wait states can be added by extending PSEN#/RD#/WR# and or by extending ALE. In these tables, Note 2 marks parameters affected by one ALE wait state, and Note 3 marks parameters affected by PSEN#/RD#/WR# wait states.

Figure 8 to Figure 13 show the bus cycles with the timing parameters.

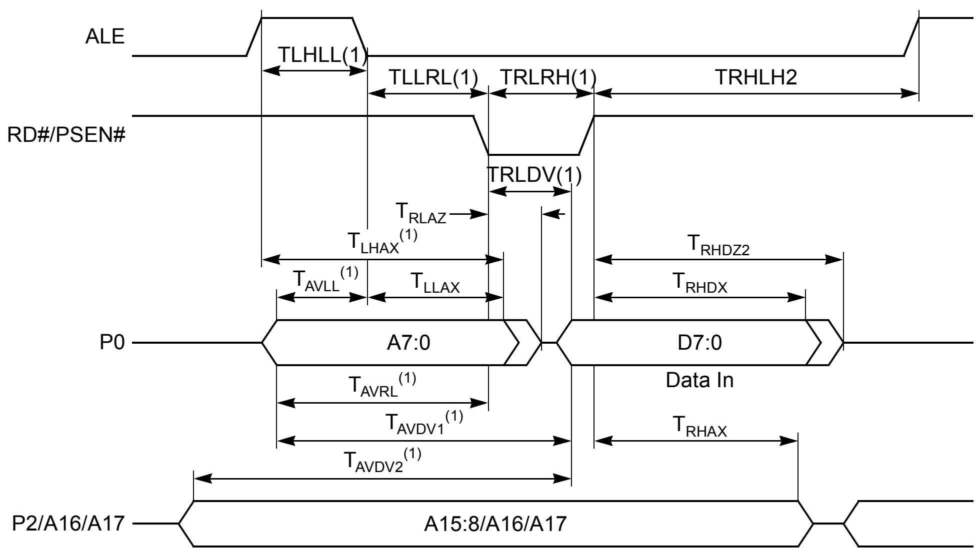
Waveforms in Non-Page Mode

Figure 8. External Bus Cycle: Code Fetch (Non-Page Mode)



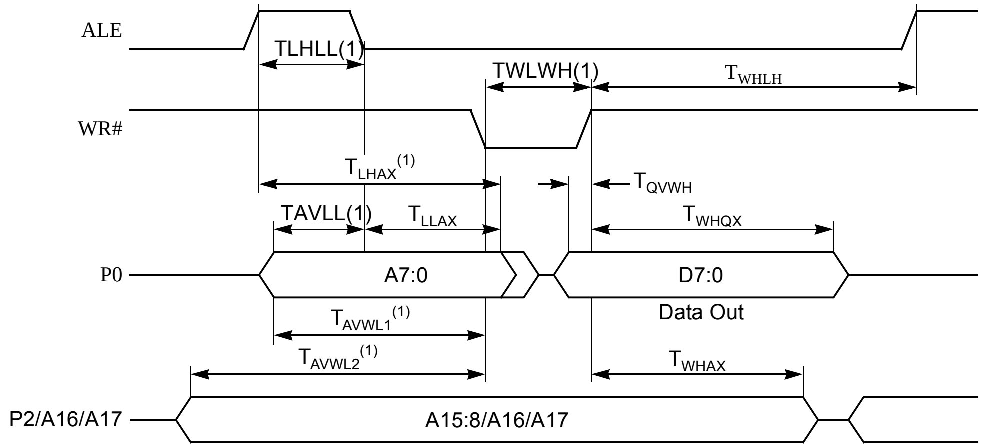
Note: 1. The value of this parameter depends on wait states. See Table 39 and Table 40.

Figure 9. External Bus Cycle: Data Read (Non-Page Mode)



Note: 1. The value of this parameter depends on wait states. See Table 39 and Table 40.

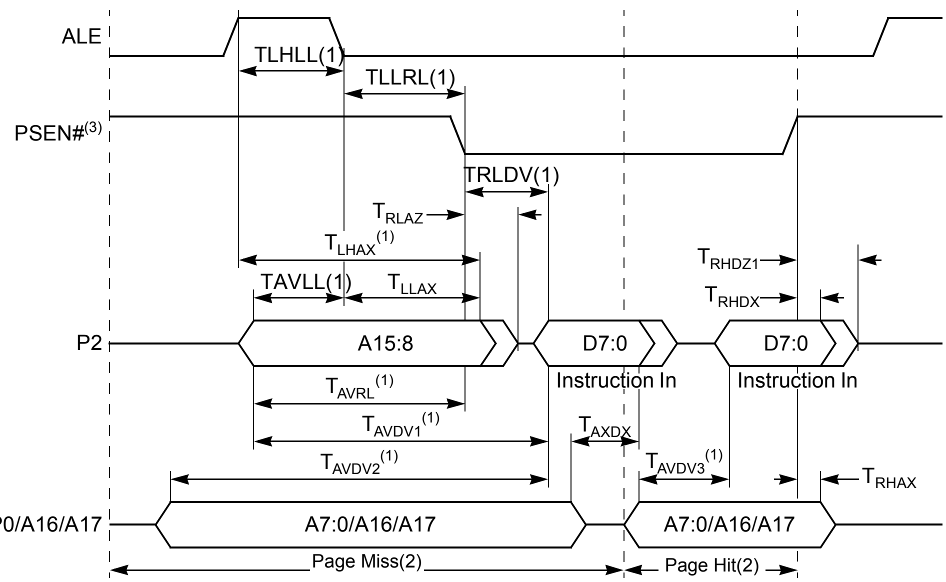
Figure 10. External Bus Cycle: Data Write (Non-Page Mode)



Note: 1. The value of this parameter depends on wait states. See Table 39 and Table 40.

Waveforms in Page Mode

Figure 11. External Bus Cycle: Code Fetch (Page Mode)

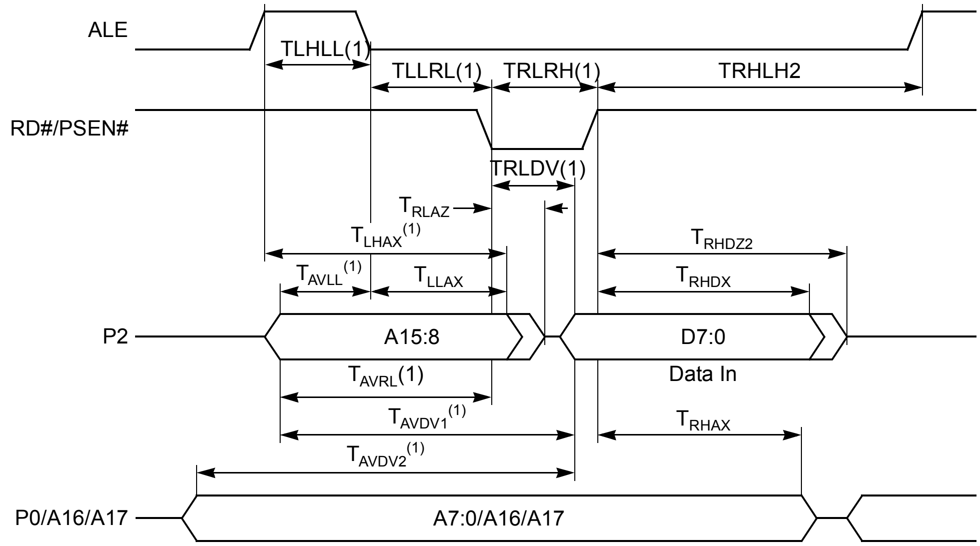


Note: 1. The value of this parameter depends on wait states. See Table 39 and Table 40.

2. A page hit (i.e., a code fetch to the same 256-byte “page” as the previous code fetch) requires one state ($2 \cdot T_{OSC}$);
a page miss requires two states ($4 \cdot T_{OSC}$).

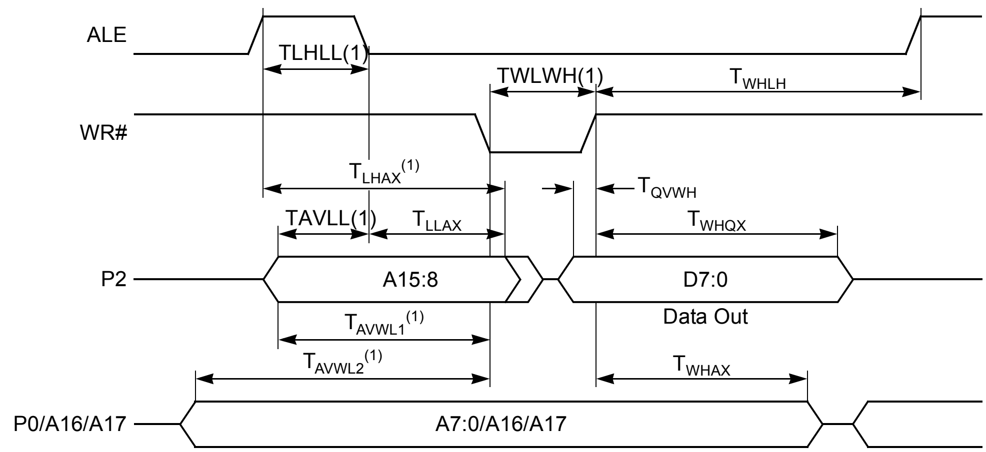
3. During a sequence of page hits, PSEN# remains low until the end of the last page-hit cycle.

Figure 12. External Bus Cycle: Data Read (Page Mode)



Note: 1. The value of this parameter depends on wait states. See Table 39 and Table 40.

Figure 13. External Bus Cycle: Data Write (Page Mode)



Note: 1. The value of this parameter depends on wait states. See Table 39 and Table 40.

AC Characteristics - Real-Time Synchronous Wait State

Definition of Symbols

Table 41. Real-Time Synchronous Wait Timing Symbol Definitions

Signals	
C	WCLK
R	RD#/PSEN#
W	WR#
Y	WAIT#

Conditions	
L	Low
V	Valid
X	No Longer Valid

Timings

Table 42. Real-Time Synchronous Wait AC Timings; V_{DD} = 2.7 to 5.5 V, T_A = -40 to 85°C

Symbol	Parameter	Min	Max	Unit
T_{CLYV}	Wait Clock Low to Wait Set-up	0	T_{OSC} - 20	ns
T_{CLYX}	Wait Hold after Wait Clock Low	$2W \cdot T_{OSC}$ + 5	$(1+2W) \cdot T_{OSC}$ - 20	ns
T_{RLYV}	PSEN#/RD# Low to Wait Set-up	0	T_{OSC} - 20	ns
T_{RLYX}	Wait Hold after PSEN#/RD# Low	$2W \cdot T_{OSC}$ + 5	$(1+2W) \cdot T_{OSC}$ - 20	ns
T_{WLYV}	WR# Low to Wait Set-up	0	T_{OSC} - 20	ns
T_{WLYX}	Wait Hold after WR# Low	$2W \cdot T_{OSC}$ + 5	$(1+2W) \cdot T_{OSC}$ - 20	ns

Waveforms

Figure 14. Real-time Synchronous Wait State: Code Fetch/Data Read

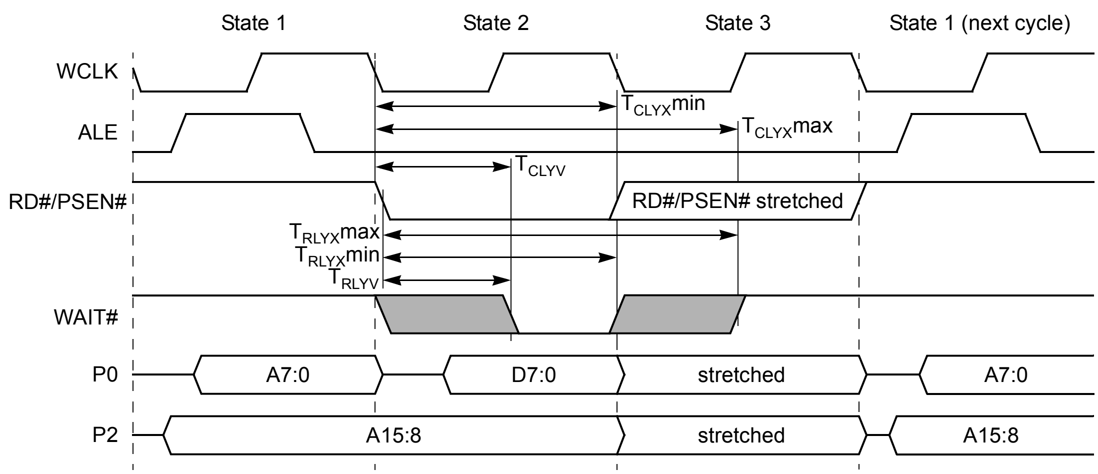
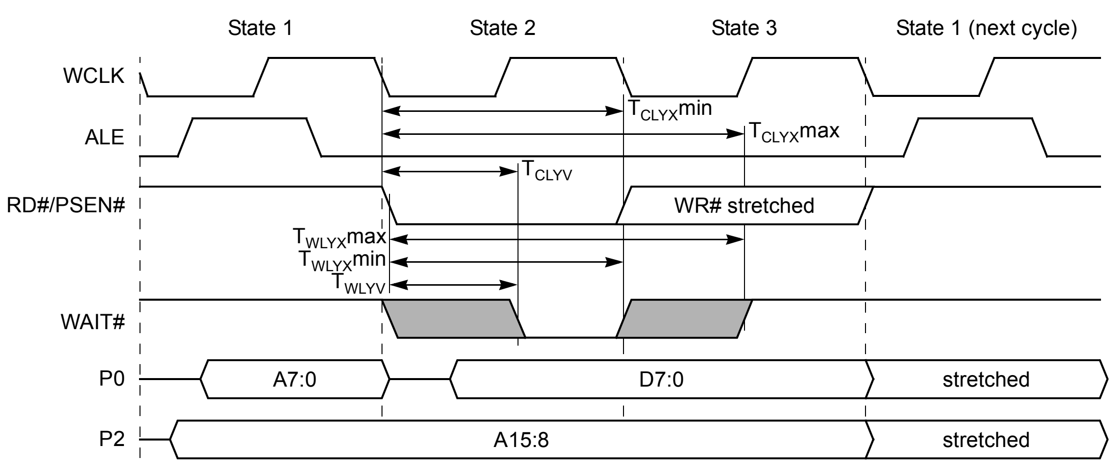


Figure 15. Real-time Synchronous Wait State: Data Write



DC Characteristics

High Speed Versions - Commercial, Industrial, and Automotive

Table 55. DC Characteristics; V_{DD} = 4.5 to 5.5 V, T_A = -40 to +85°C

Symbol	Parameter	Min	Typical(4)	Max	Units	Test Conditions
V_{IL}	Input Low Voltage (except EA#, SCL, SDA)	-0.5		$0.2{\cdot}V_{DD}$ - 0.1	V	
V_{IL1}(5)	Input Low Voltage (SCL, SDA)	-0.5		$0.3{\cdot}V_{DD}$	V	
V_{IL2}	Input Low Voltage (EA#)	0		$0.2{\cdot}V_{DD}$ - 0.3	V	
V_{IH}	Input high Voltage (except XTAL1, RST, SCL, SDA)	$0.2{\cdot}V_{DD}$ + 0.9		V_{DD} + 0.5	V	
V_{IH1}(5)	Input high Voltage (XTAL1, RST, SCL, SDA)	$0.7{\cdot}V_{DD}$		V_{DD} + 0.5	V	
V_{OL}	Output Low Voltage (Ports 1, 2, 3)			0.3 0.45 1.0	V	I_{OL} = 100 µA(1)(2) I_{OL} = 1.6 mA(1)(2) I_{OL} = 3.5 mA(1)(2)
V_{OL1}	Output Low Voltage (Ports 0, ALE, PSEN#, Port 2 in Page Mode during External Address)			0.3 0.45 1.0	V	I_{OL} = 200 µA(1)(2) I_{OL} = 3.2 mA(1)(2) I_{OL} = 7.0 mA(1)(2)
V_{OH}	Output high Voltage (Ports 1, 2, 3, ALE, PSEN#)	V_{DD} - 0.3 V_{DD} - 0.7 V_{DD} - 1.5			V	I_{OH} = -10 µA(3) I_{OH} = -30 µA(3) I_{OH} = -60 µA(3)
V_{OH1}	Output high Voltage (Port 0, Port 2 in Page Mode during External Address)	V_{DD} - 0.3 V_{DD} - 0.7 V_{DD} - 1.5			V	I_{OH} = -200 µA I_{OH} = -3.2 mA I_{OH} = -7.0 mA
V_{RET}	V_{DD} data retention limit			1.8	V	
I_{IL0}	Logical 0 Input Current (Ports 1, 2, 3)			- 50	µA	V_{IN} = 0.45 V
I_{IL1}	Logical 1 Input Current (NMI)			+ 50	µA	V_{IN} = V_{DD}
I_{LI}	Input Leakage Current (Port 0)			± 10	µA	0.45 V < V_{IN} < V_{DD}
I_{TL}	Logical 1-to-0 Transition Current (Ports 1, 2, 3 - AWAIT#)			- 650	µA	V_{IN} = 2.0 V
R_{RST}	RST Pull-Down Resistor	40	110	225	kΩ	
C_{IO}	Pin Capacitance		10		pF	T_A = 25°C
I_{DD}	Operating Current		20 25 35	25 30 40	mA	F_{OSC} = 12 MHz F_{OSC} = 16 MHz F_{OSC} = 24 MHz
I_{DL}	Idle Mode Current		5 6.5 9.5	8 10 14	mA	F_{OSC} = 12 MHz F_{OSC} = 16 MHz F_{OSC} = 24 MHz
I_{PD}	Power-Down Current		2	20	µA	V_{RET} < V_{DD} < 5.5 V
V_{PP}	Programming supply voltage	12.5		13	V	T_A = 0 to +40°C
I_{PP}	Programming supply current			75	mA	T_A = 0 to +40°C

Notes: 1. Under steady-state (non-transient) conditions, I_{OL} must be externally limited as follows:

Maximum IOL per port pin: 10 mA

Maximum IOL per 8-bit port:Port 0 26 mA

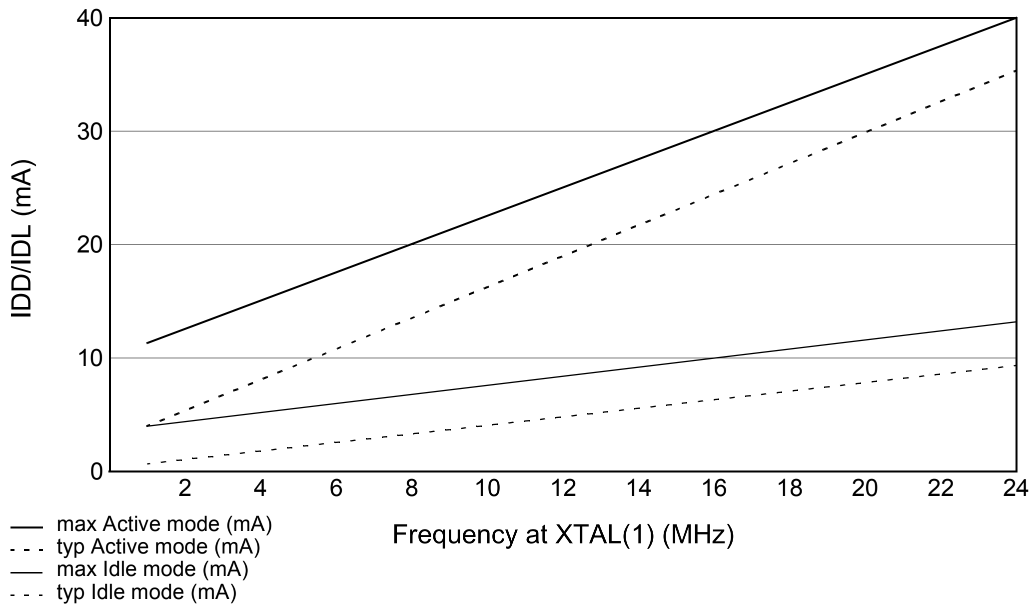
Ports 1-3 15 mA

Maximum Total IOL for all: Output Pins 71 mA

If IOL exceeds the test conditions, VOL may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.

2. Capacitive loading on Ports 0 and 2 may cause spurious noise pulses above 0.4 V on the low-level outputs of ALE and Ports 1, 2, and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins change from high to low. In applications where capacitive loading exceeds 100 pF, the noise pulses on these signals may exceed 0.8 V. It may be desirable to qualify ALE or other signals with a Schmitt Trigger or CMOS-level input logic.
3. Capacitive loading on Ports 0 and 2 causes the V_{OH} on ALE and PSEN# to drop below the specification when the address lines are stabilizing.
4. Typical values are obtained using V_{DD} = 5 V and T_A = 25°C. They are not tested and there is not guarantee on these values.
5. The input threshold voltage of SCL and SDA meets the TWI specification, so an input voltage below $0.3 \cdot V_{DD}$ will be recognized as a logic 0 while an input voltage above $0.7 \cdot V_{DD}$ will be recognized as a logic 1.

Figure 28. I_{DD}/I_{DL} Versus Frequency; V_{DD} = 4.5 to 5.5 V



Note: 1. The clock prescaler is not used: $F_{OSC} = F_{XTAL}$.

PLCC 44 - Mechanical Outline

Figure 35. Plastic Lead Chip Carrier

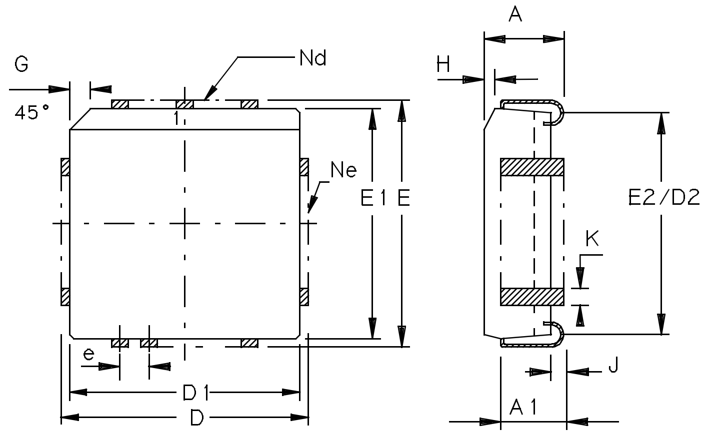


Table 59. PLCC Package Size

	MM		Inch	
	Min	**Max**	**Min**	**Max**
A	4.20	4.57	.165	.180
A1	2.29	3.04	.090	.120
D	17.40	17.65	.685	.695
D1	16.44	16.66	.647	.656
D2	14.99	16.00	.590	.630
E	17.40	17.65	.685	.695
E1	16.44	16.66	.647	.656
E2	14.99	16.00	.590	.630
e	1.27 BSC		.050 BSC	
G	1.07	1.22	.042	.048
H	1.07	1.42	.042	.056
J	0.51	-	.020	-
K	0.33	0.53	.013	.021
Nd	11		11	
Ne	11		11	

CQPJ 44 with Window - Mechanical Outline

Figure 36. Ceramic Quad Pack J

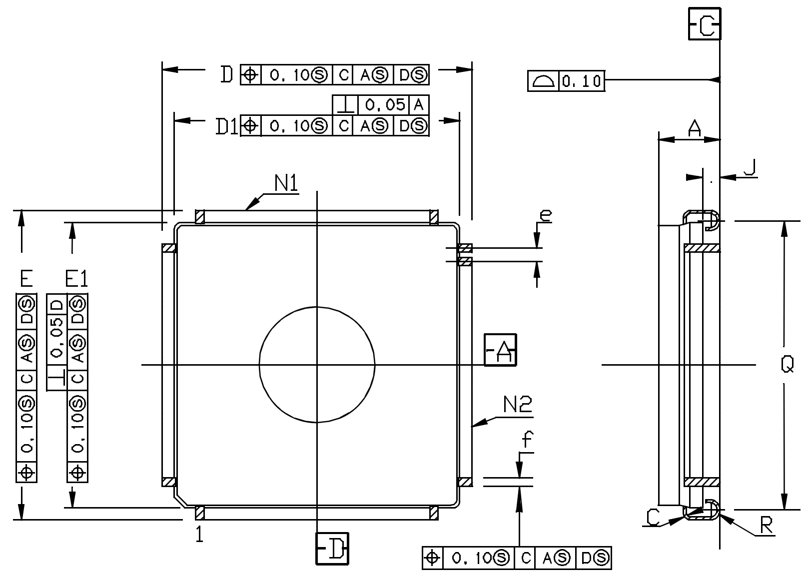


Table 60. CQPJ Package Size

	MM		Inch	
	Min	Max	Min	Max
A	-	4.90	-	.193
C	0.15	0.25	.006	.010
D - E	17.40	17.55	.685	.691
D1 - E1	16.36	16.66	.644	.656
e	1.27 TYP		.050 TYP	
f	0.43	0.53	.017	.021
J	0.86	1.12	.034	.044
Q	15.49	16.00	.610	.630
R	0.86 TYP		.034 TYP	
N1	11		11	
N2	11		11	